

# Power Inductor

## BMMN Series



### Overview

Power inductors are passive electronic components used in various circuits to store energy in a magnetic field when electrical current flows through them. They are critical in filtering, energy storage, and noise suppression in power electronic systems. They are designed to handle higher currents and are optimized for minimal power loss and thermal efficiency. This series is the most common standard specification.

### Benefits

1. Automotive grade available
2. Energy Storage, Efficiently stores and transfers energy in DC-DC converters and power supplies.
3. High Current Handling, Supports high current capacity with minimal losses, ensuring thermal stability.
4. Compact and Efficient Design, Advanced materials and construction enable miniaturization without sacrificing performance, ideal for space-constrained designs.

### Applications

1. Automotive Systems for ADAS, infotainment.
2. Industrial Equipment: Robotics, power tools, industrial automation, and IoT devices.
3. DC-DC converters, inverters, and battery management systems.
4. Base stations, 5G infrastructure, and signal processing systems.
5. Consumer Electronics: Smartphones, laptops, tablets, wearable devices, and gaming consoles.

### Product Information

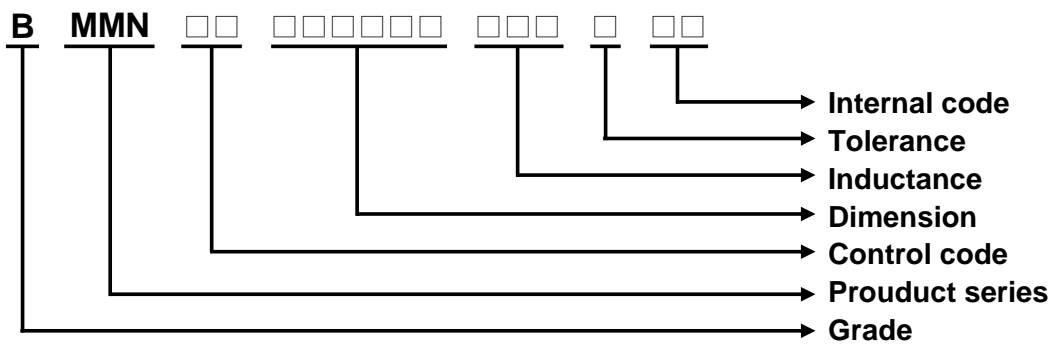
Series	L (mm)	W(mm)	T (mm)	Inductance (μH)
BMMN	5.18	5.49	1.2	0.18 ~ 47
	5.18	5.49	1.5	
	5.18	5.49	1.8	
	4.7	5.3	3.0	
	6.47	6.86	1.5	
	6.6	7.4	1.8	
	6.6	6.95	3.0	
	10	11.5	2.0	
	10	11.5	3.0	
	10	11.5	4.0	
	12.9	13.2	5.0	
	12.6	14.2	6.0	
	12.6	13.2	6.5	
	17.2	17.6	7.00	



## BMMN00171770 Series Specification

**1 Scope** This specification applies to large current and low loss SMD power inductor

### 2 Part numbering



### 3 Temperature rating

Operating Temperature: -55°C~125°C

Storage Temperature: (on tape & reel): -20°C to +40°C; 75% RH max.

### 4 Marking



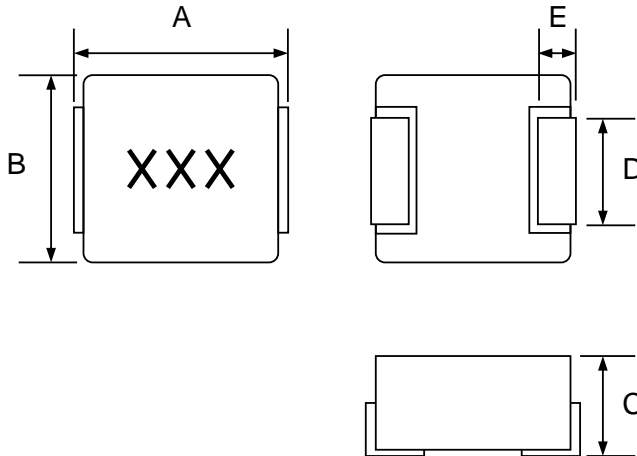
Marking : 100

### 5 Standard testing condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH

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### 6 Configuration and dimensions



Dimensions in mm

Type	171770
A	17.6 ± 0.5
B	17.2 Max
C	7.0 Max
D	11.8 ± 0.3
E	2.5 ± 0.5

Size Code	Net weight(grms)
171770	12 (typ.)

### 7 Electrical characteristics

Part number	Inductance (uH)	Tolerance (±%)	Test Freq.	I <sub>rms</sub> (A) Typ.	I <sub>sat</sub> (A) Typ.	RDC (mΩ) Max.(Typ.)	Marking
BMMN00171770100MX2	10	20	100kHz,0.5V	14	18	10(9.3)	100

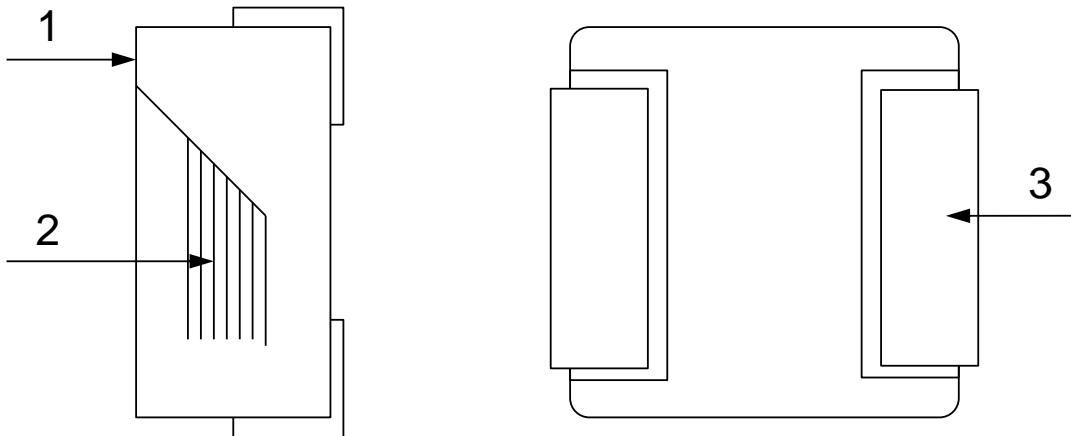
#### Note:

1. Operating temperature range -55°C to 125°C.
2. I<sub>sat</sub> for Inductance drop 30% from its value without current.
3. I<sub>rms</sub> for a 40°C temperature rise from 25°C ambient.
4. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design 125°C under worst case operating conditions. Component placement, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
5. Absolute maximum voltage 30V DC. (Based on test method, it may not be the same under different application, it is recommended to verify first.)

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### 8 BMMN00171770 Series

#### 8.1 Construction



#### 8.2 Material List

Item	Part	Description
1	Magnetic core	Magnetic metal powder
2	Coil	Enameled copper wire
3	Terminals	Copper based terminal

# BMMN00171770 Series Specification

## 9 Reliability test items

### 1-1.Mechanical Performance

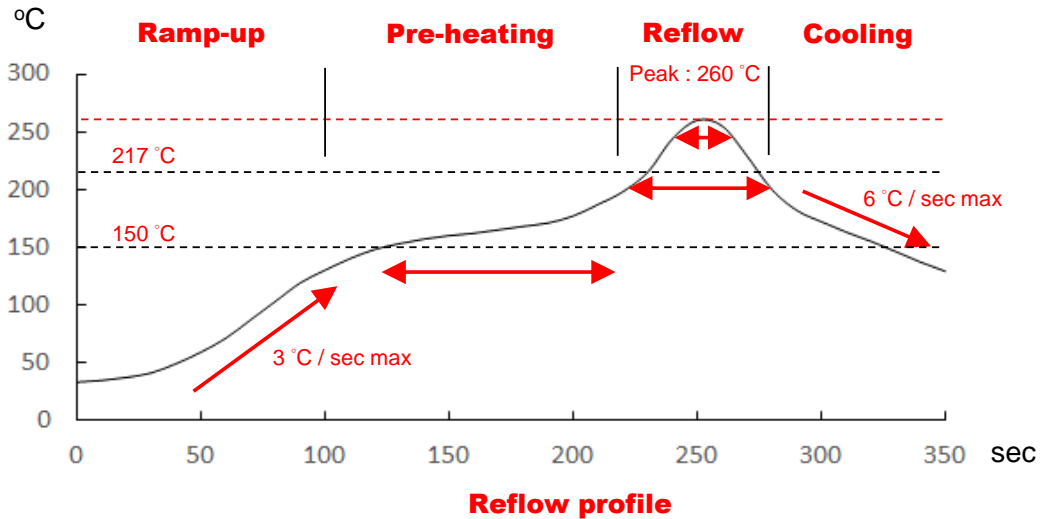
No	Item	Specification	Test Method
1-1-1	Vibration	Appearance: No damage Inductance: within $\pm 10\%$ of initial value	Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-2	Resistance to Soldering Heat	Appearance: No damage	Pre-heating: 150°C, 1min Solder Composition: Sn/Ag3.0/Cu0.5 Solder Temperature: 260 $\pm$ 5°C Immersion Time: 10 $\pm$ 1sec
1-1-3	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150°C, 1min Solder Composition: Sn/Ag3.0/Cu0.5 Solder Temperature: 245 $\pm$ 5°C Immersion Time: 4 $\pm$ 1sec
1-1-4	Resistance to solvent	There must be no change in appearance or obliteration of marking.	Inductors must withstand 6 minutes of alcohol or water.

### 1-2.Environmental Performance

No	Item	Specification	Test Method															
1-2-1	Temperature Shock	Appearance: No damage Inductance: within $\pm 10\%$ of initial value	10 cycles (Air to Air) 1 cycles shall consist of: 30 minutes exposure to -55°C 30 minutes exposure to 125°C 15 seconds maximum transition between temperatures															
1-2-2	Temperature Cycle		One cycle: <table border="1"> <thead> <tr> <th>Step</th> <th>Temperature (°C)</th> <th>Time (min)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-55<math>\pm</math>3</td> <td>30</td> </tr> <tr> <td>2</td> <td>25<math>\pm</math>2</td> <td>3</td> </tr> <tr> <td>3</td> <td>125<math>\pm</math>3</td> <td>30</td> </tr> <tr> <td>4</td> <td>25<math>\pm</math>2</td> <td>3</td> </tr> </tbody> </table>	Step	Temperature (°C)	Time (min)	1	-55 $\pm$ 3	30	2	25 $\pm$ 2	3	3	125 $\pm$ 3	30	4	25 $\pm$ 2	3
Step	Temperature (°C)	Time (min)																
1	-55 $\pm$ 3	30																
2	25 $\pm$ 2	3																
3	125 $\pm$ 3	30																
4	25 $\pm$ 2	3																
1-2-3	Humidity Resistance		Total: 100cycles Measured after exposure in the room condition for 24hrs Temperature: 40 $\pm$ 2°C Relative Humidity: 90 ~ 95% Time: 1000hrs Measured after exposure in the room condition for 24hrs															
1-2-4	Heat Life		Temperature: 85 $\pm$ 3°C Relative Humidity: 20% Applied Current: Rated Current Time: 1000hrs Measured after exposure in the room condition for 24hrs															
1-2-5	Cold Resistance		Temperature: -55 $\pm$ 3°C Relative Humidity: 0% Time: 1000hrs Measured after exposure in the room condition for 24hrs															

## BMMN00171770 Series Specification

### 10 Recommended IR reflow profile



Lead-Free(LF)

Refer to J-STD-020F

Item	Ramp-up	Pre-heating	Reflow	Peak Temp.	Cooling
Temp. scope	R.T. ~150 °C	150 °C~200 °C	217 °C	260±5 °C	Peak Temp. 150 °C
Time spec	-	60~120 sec	60~150 sec	20~40 sec	-

Note:

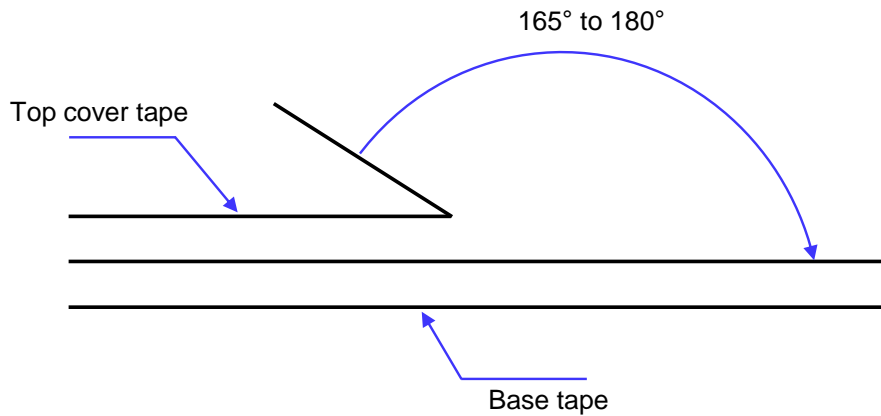
1. IR reflow times: within 3 times
2. Nitrogen adopted is recommended while in IR reflow

## BMMN00171770 Series Specification

### 11 Packaging

#### 11.1 Packaging-cover tape

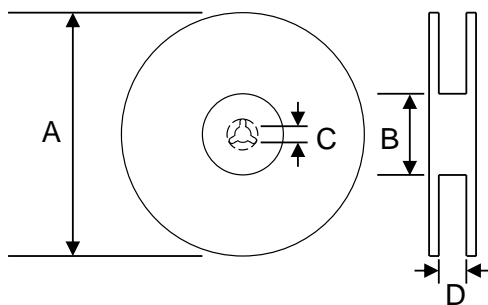
The force for tearing off cover tape is 10 to 130 grams.



#### 11.2 Packaging quantity

Type	pcs/reel
171770	100

#### 11.3 Reel dimensions



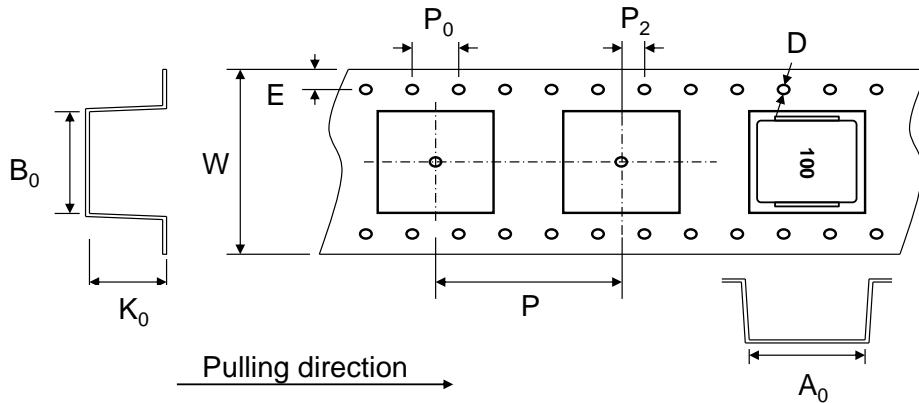
Dimensions in mm

Type	A	B	C	D
171770	330	100	13	32

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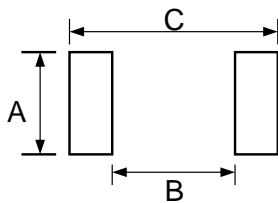
### 11 Packaging

#### 11.4 Tape dimensions in mm



Type	A <sub>0</sub>	B <sub>0</sub>	K <sub>0</sub>	D	E	W	P	P <sub>0</sub>	P <sub>2</sub>
171770	17.45	18.5	7.8	1.5	1.75	32	24	4	2

### 12 Recommended pattern



Dimensions in mm

Type	A	B	C
171770	12.8	11.2	18.2

### 13 Note

1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
2. Don't design/mount any components in contact with this product.
3. The moisture sensitivity level (MSL) of products is classified as level 1.
4. Shelf life: 1 years from the date of shipment.

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**14** Graph

